

# Modeling of Automotive Wheel-Speed Sensor IC's in SystemC

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# Agenda

## ■ Outline:

- Time before System(C) models
- Overview of Infineon's SystemC models
- A look at SystemC models for customers
- How Infineon is modeling a SystemC model
- An example of a SystemC model for customers and IFX internally
  - Black-box approach with embedded models in Matlab/Simulink
  - VHDL and SystemC co-simulations
- New approaches ...
- Summary
- Discussions and questions ...



# Look into History

## ■ Starting point in the past (Time before SystemC models):

### □ Discussions with customer:

- Review of data-sheet regarding chip-behavior (Telecons, face2face meetings etc.)
- Possible misinterpretation of specifications
- Verification of digital algorithm behavior on silicon-level → “late-surprises” → needed redesign-steps → loose of time and money



### □ Internal discussions with concept-engineer vs. chip-designer etc.)

- Review of internal documentation
- Possible misinterpretation of specifications internally
- No “golden/reference” model available for pre-silicon verification



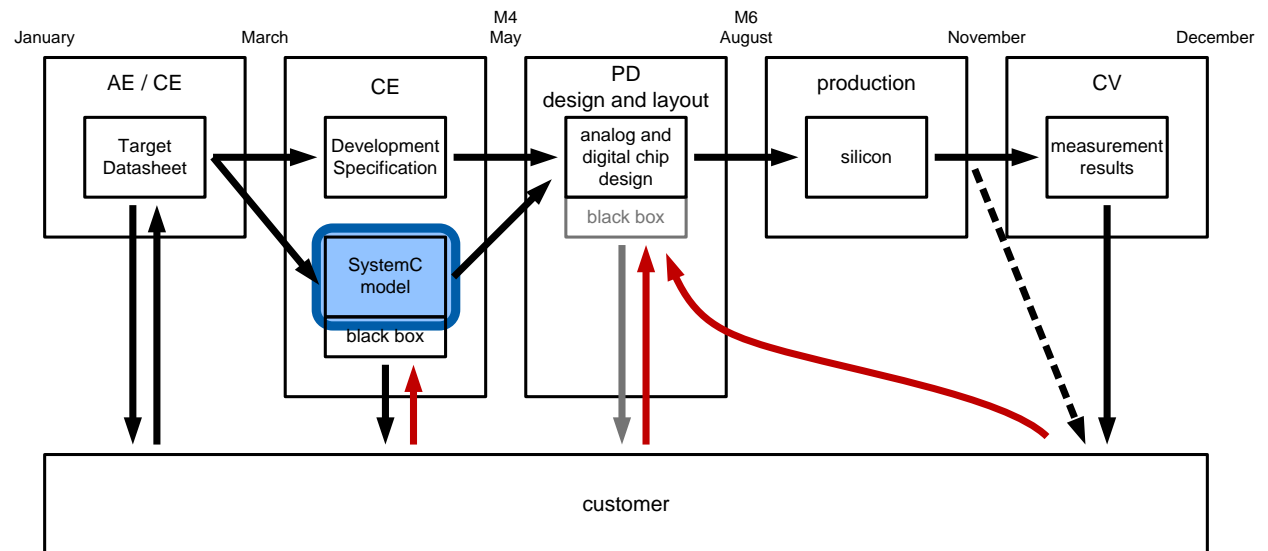
# General Aspects

## ■ Overview of SystemC models today:

- ❑ Infineon (department Sense & Control) is using SystemC-models for mechanical, thermal and electrical investigations for automotive sensor products for several years
- ❑ SystemC models of sensor products (e.g. speed-, angle and linear Hall sensor) were delivered to several customers
- ❑ SystemC models are also used for internal co-simulation with VHDL → internal verification (“Executable Specification”)
- ❑ Design-flow with the usage of SystemC-models:

### Example Wheel Speed Sensor Project:

AE=Application Engineering  
 CE=Concept Engineering  
 PD=Product Design  
 CV=Comonent Verification



# Motivation for SystemC/SystemC-AMS Models

## ■ Advantages of using SystemC models for customers and Infineon:

- Allow customer testing of chip features in a very early design step (before tape-out)
- Reduction of development costs (e.g. avoiding redesigns etc.)
  - Time to market / First time right
- Increase internal understanding of chip architecture and concept
- Avoiding miss-interpretation of the specification
- An accurate system model can deliver:
  - Understanding of the internal digital-algorithms, state-machines and output-protocols
  - Implementation of main signal processing flow (of analog- and digital-section)



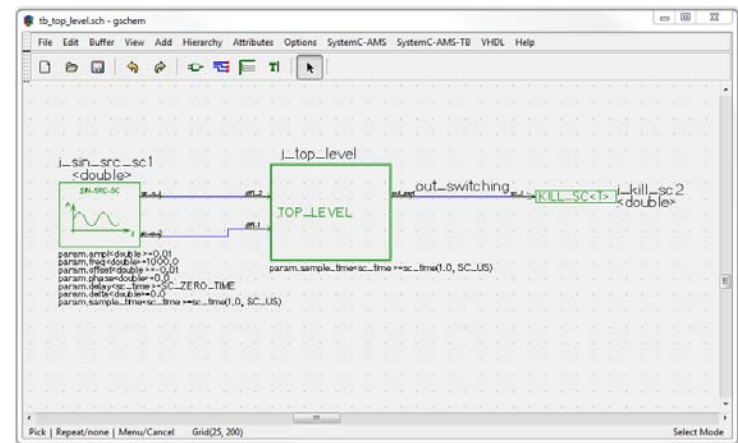
# Customer & Internal Model of an ABS Speed-Sensor (TLE4941plusC)

## ■ Analog blocks modeled „ideal“ → fast simulations results:

- No internal offsets
- Mismatch of transistors not considered (e.g. process variations)
- Implementation of temperature dependence (optional)
- UV/OV behavior can be seen
- Current interface (7mA/14mA)

## ■ Digital Core (detailed implemented):

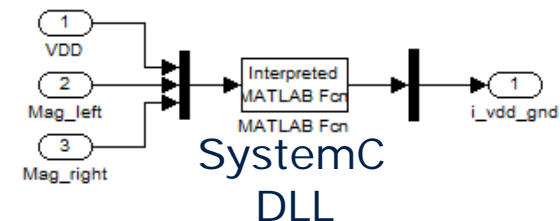
- System clocking
- Digital algorithm implemented detailed
- ADC/DAC granularity (typical signal-ranges)
- Digital output-protocol



# SystemC/SystemC-AMS Models for Customers

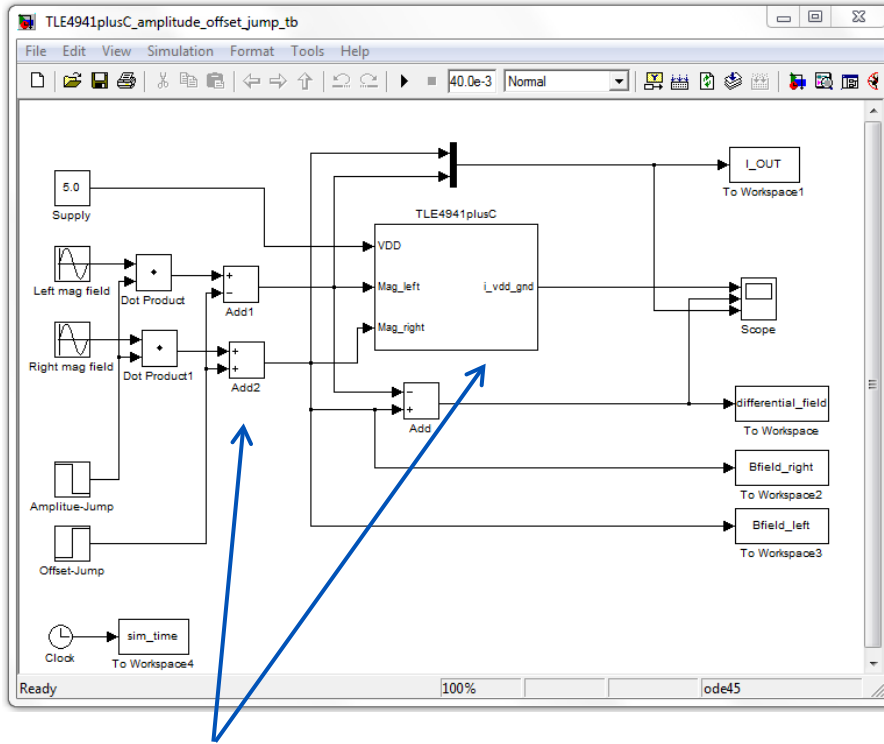
## ■ SystemC models for customers:

- Blackbox approach of embedded SystemC models in Matlab/Simulink → usage of a DLL
- Customers can use their own specific testbenches in Matlab or Simulink
- Customers can simulate behavior of IC, but have no detailed information about Infineon IP (algorithms etc.)
  - Simulating sensor-model with ECU-model long before silicon is available
- Customers are requesting for system models to check the behavior of the IC
- Optional Microsoft Excel interface → Providing input-file and/or storing simulation data in MS Excel format

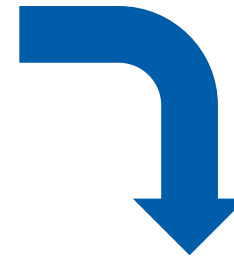


# Embedded SystemC Model in Simulink

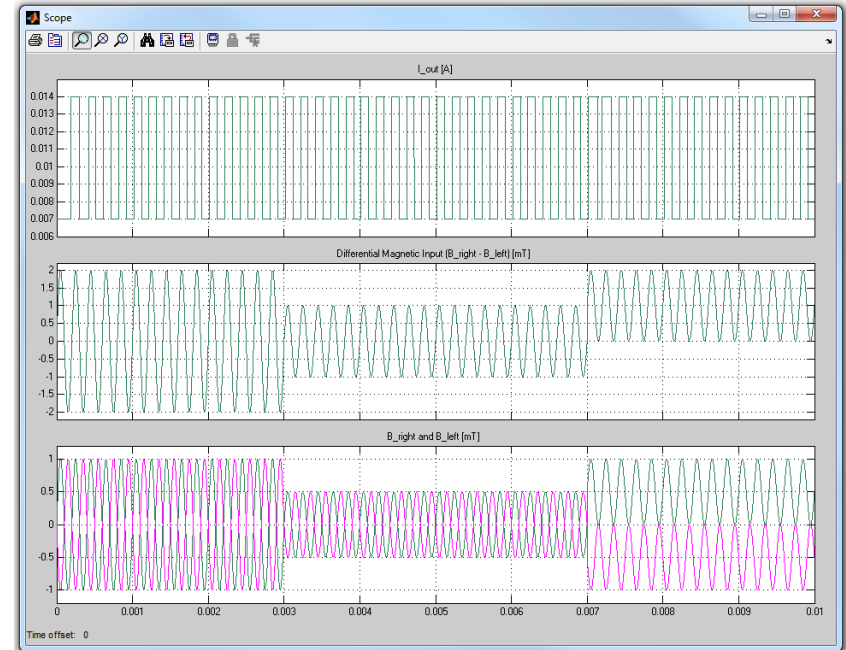
## ■ Simulink model of TLE4941plusC and simulation results:



Simulink Top-level testbench & embedded SystemC model (DLL)



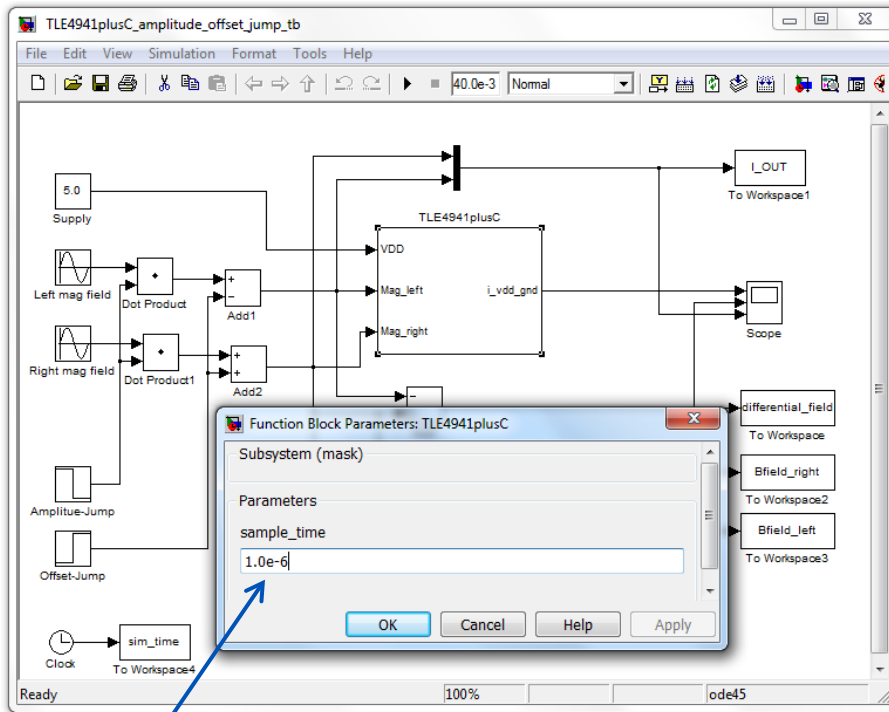
Simulation results:



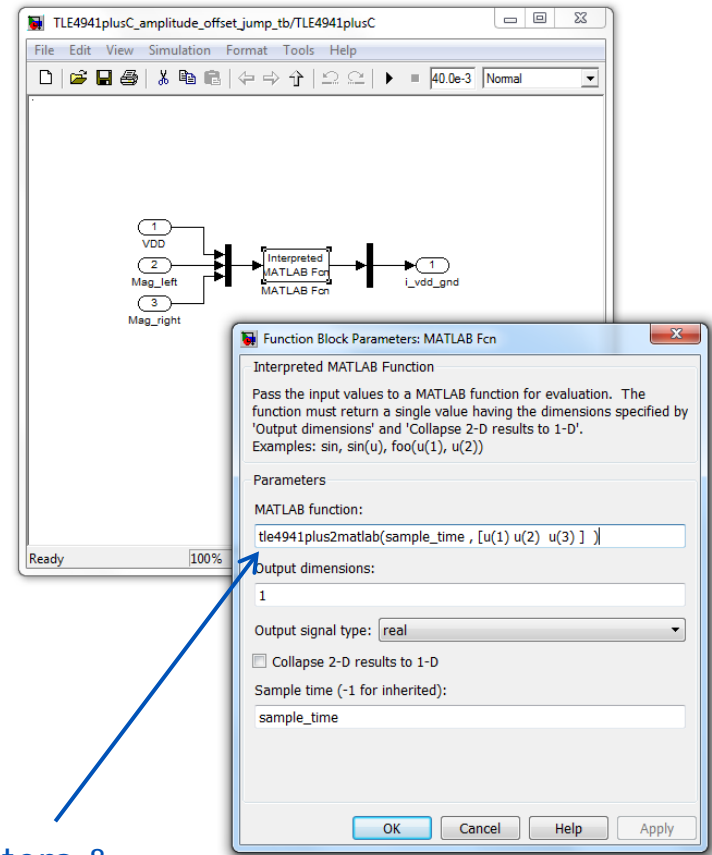


# Detailed View of a SystemC Model in Simulink

- A “look” under the mask of an embedded SytemC / Simulink customer model:



Sample-Time

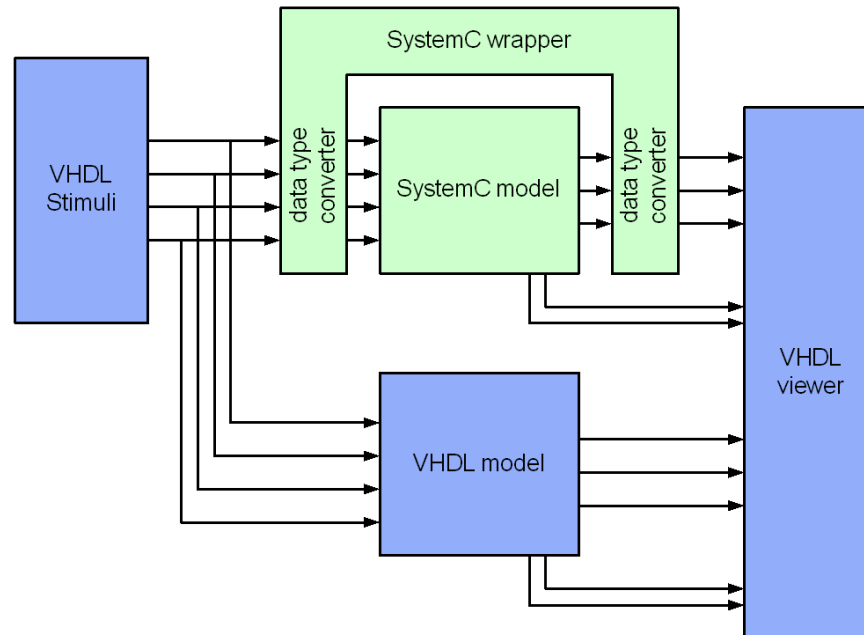


Input-Parameters & Call of DLL-function

# VHDL & SystemC co-simulation

## ■ VHDL & SystemC environment for verification of implementation:

- VHDL and SystemC should get equal stimuli from VHDL test-bench
- Output ports and internal signals of VHDL and SystemC should be traced by ModelSim



- SystemC wrapper (possibly) required to convert data types such as SystemC-double to SystemC-integer
- Additionally, a data type conversion (possibly) required in VHDL test-bench to convert data types such as VHDL-analog to VHDL-integer

# VHDL2SystemC Converter

- New approach → Usage of VHDL2SystemC converter:

- “Quasi” automatic conversion of digital-core units possible → bit-true conversion

- Additionally analog basic blocks could be converted → optional

- Advantages for customer and IFX:

- Faster conversion of VHDL-code to System-C

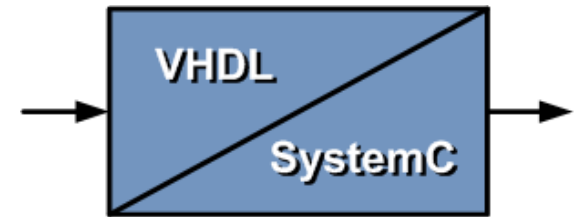
- Lower risk of misinterpretation of VHDL-code

- Delivery of a SystemC model possible before tape-out

- Points which have to be still reviewed/considered:

- Behavior of the model should be the same as the behavior of the VHDL simulations

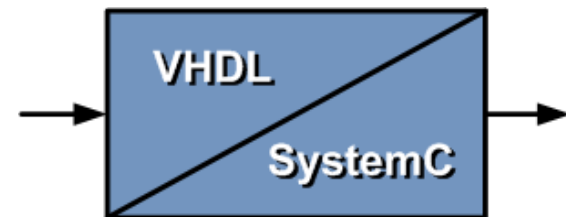
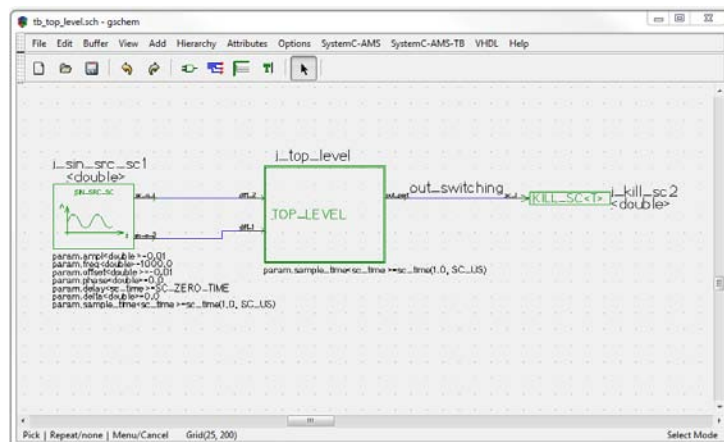
- Digital- and (analog-) top-level wire connections have to be done manually



# Summary and Outlook

## ■ Summary:

- ❑ SystemC models are used internally for VHDL-co-simulation as well as for customer-models for golden reference
- ❑ Very positive customer response to this methodology
- ❑ This approach results in faster development-cycles and prevent possible expensive and time-consuming re-designs.
- ❑ Next step is to use a “quasi” automatic conversion of digital blocks with a VHDL to SystemC converter, to generate models with implementation details, fast and efficient.



# Thank you for Paying Attention! Do you have any Questions?

Special thanks to FHG Dresden who support us in all SystemC activities!



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